



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts,Customers Priority,Honest Operation,and Considerate Service",our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

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Email & Skype: info@chipsmall.com Web: www.chipsmall.com

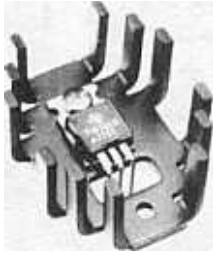
Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



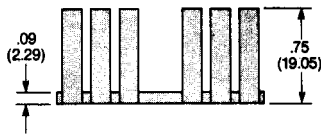
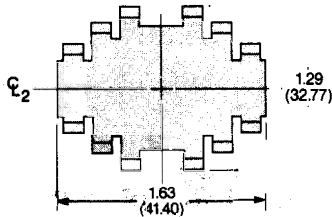
SECTION 2

HEAT DISSIPATORS FOR PLASTIC CASE, CASE-MOUNTED SEMICONDUCTORS

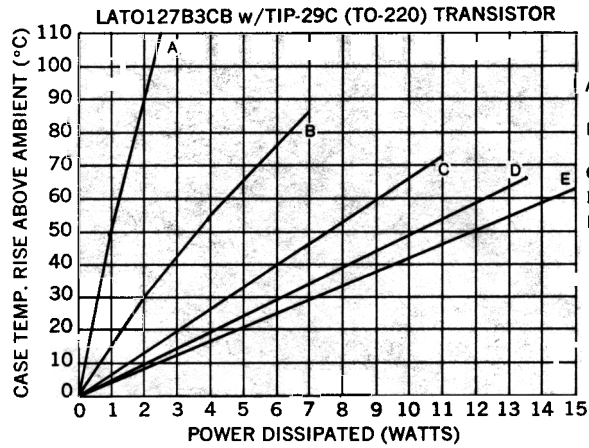
LA-B3 Series



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Dimensions are for reference use only. Contact IERC for dimensions with tolerances or standard part drawings.



DESCRIPTION OF CURVES
 A. N.C. Horiz. Device Only Mounted to G-10.
 B. N.C. Horiz. & Vert. With Dissipator.
 C. 200 FPM w/Diss.
 D. 500 FPM w/Diss.
 E. 1000 FPM w/Diss.

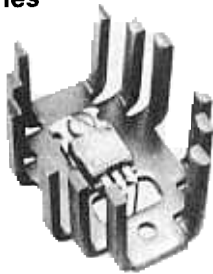
- Thermal Resistance Case to Sink is 0.9-1.1 °C/W w/Joint Compound.
- Derate 0.7 °C/watt for unplated part in natural convection only.
- Derate 3.0 °C/watt for Insulube® part in natural convection only.

Ordering Information

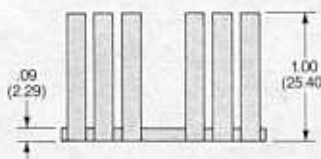
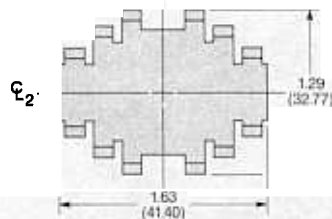
IERC PART NO.				Semiconductor Accommodated	Hole patt. ref. no. (see pg. 2-27)	Max. Weight (Grams)
Unplated	Comm'l. Black Anodize	Mil. Black Anodize	Insulube® 448			
LA000B3U	LA000B3CB	LA000B3B	LA000B3	Undrilled	—	10.8
LATO126B3U	LATO126B3CB	LATO126B3B	LATO126B3	TO-126	2	10.8
LATO127B3U	LATO127B3CB	LATO127B3B	LATO127B3	TO-127, TO-220	3	10.8
LA394B3U	LA394B3CB	LA394B3B	LA394B3	Universal	4	10.8

Note: See page iv for other finishes.

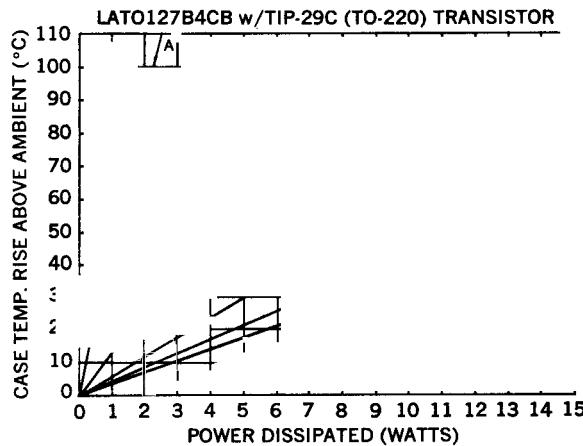
LA-B4 Series



ϕ₁



Dimensions are for reference use only. Contact IERC for dimensions with tolerances or standard part drawings.



DESCRIPTION OF CURVES
 A. N.C. Horiz. Device Only Mounted to G-10.
 B. N.C. Horiz. & Vert. With Dissipator.
 C. 200 FPM w/Diss.
 D. 500 FPM w/Diss.
 E. 1000 FPM w/Diss.

- Thermal Resistance Case to Sink is 0.9-1.1 °C/W w/Joint Compound.
- Derate 0.7 °C/watt for unplated part in natural convection only.
- Derate 3.0 °C/watt for Insulube® part in natural convection only.

Ordering Information

IERC PART NO.				Semiconductor Accommodated	Hole patt. ref. no. (see pg. 2-27)	Max. Weight (Grams)
Unplated	Comm'l. Black Anodize	Mil. Black Anodize	Insulube® 448			
LA000B4U	LA000B4CB	LA000B4B	LA000B4	Undrilled	—	12.9
LATO126B4U	LATO126B4CB	LATO126B4B	LATO126B4	TO-126	2	12.9
LATO127B4U	LATO127B4CB	LATO127B4B	LATO127B4	TO-127, TO-220	3	12.9
LA394B4U	LA394B4CB	LA394B4B	LA394B4	Universal	4	12.9

Note: See page iv for other finishes.